

## ABSTRACT OF THE DISCLOSURE

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The present invention provides a stacked chip package having a heat transfer wire. The heat transfer wire is disposed between the stacked chips and at least one end of the transfer wire is connected to a dummy board pad provided on a board. Therefore, the heat generated by the chips and trapped between the chips can be effectively dissipated.

## FIGURE TO BE PUBLISHED

FIG. 5

## INDEX

10 Stack, Heat, Dissipation, Wire, Package